

INVERTED MICROVIA STRUCTURE AND METHOD OF MANUFACTURE

ABSTRACT

A multilayer circuit board (50) includes a plurality of substrate cores (34 and 44), an adhesive / bonding layer (55) between at least two among the plurality of substrate cores, and a microvia (35 and 45) in each of at least two of the plurality of substrate cores. The microvia includes a conductive interconnection (39) between a top conductive surface and a bottom conductive surface of each of the plurality of substrate cores and the microvia in a first substrate core is arranged to be inverted relative to a microvia in a second substrate core. The multilayer circuit board can further include a plated through-hole (54) through the plurality of substrate cores and the adhesive / bonding layer such that at least two among the top conductive surfaces (32 or 46) and the bottom conductive surfaces (36 or 42) of the plurality of substrate cores are connected.